

QUALITY
FIRST

OS-IN-2020-003

Additional Plasma Cleaning for OSLON Compact PL Multichip

Customer Information Package

OS QM CQM A | 03.02.2020

Light is OSRAM

OSRAM
Opto Semiconductors

OS-IN-2020-003

Additional Plasma Cleaning for OSLON Compact PL Multichip

Reason of Change

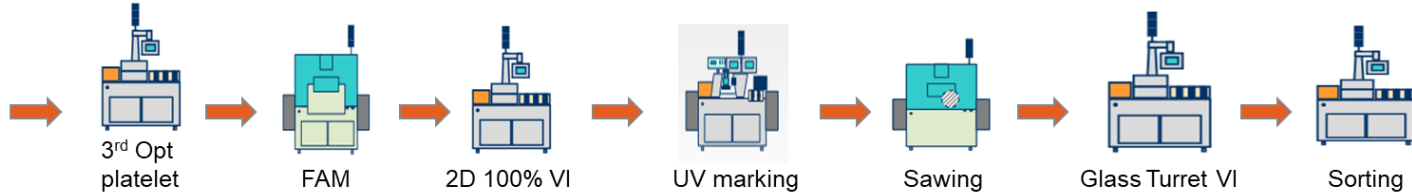
Quality improvement due to enhanced white mold compound adhesion towards ceramic substrate.

No change in fit, form, function and reliability of affected products.

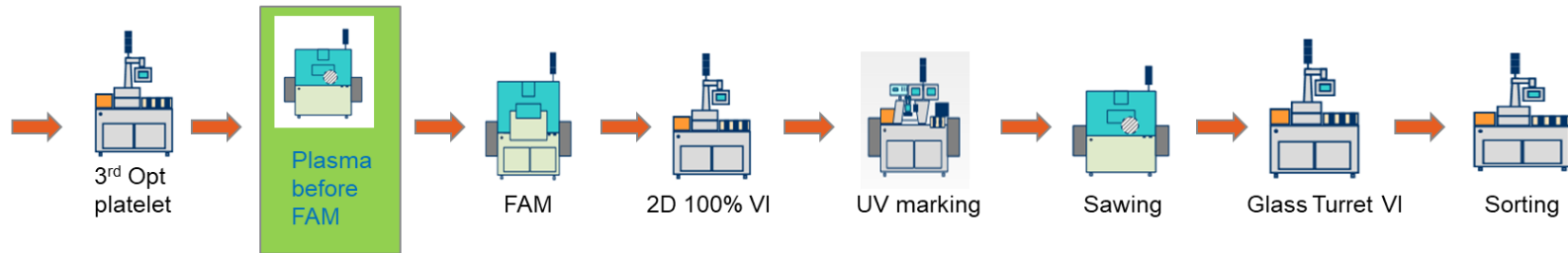
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Additional Plasma Cleaning for OSLOM Compact PL Multichip

Current Process Flow



Target Process Flow



 New added Plasma before FAM process

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Additional Plasma Cleaning for OSLON Compact PL Multichip

Affected Products

Product Name
KW2 CFLNM1.TG
KW3 CGLNM1.TG
KW4 CHLNM1.TG

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Time Schedule

Changes will be applied starting CW09.

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Thank you.

Products Affected by Information Notification

Number: OS-IN-2020-003

Name: Additional Plasma Cleaning for OSOLON Compact PL Multichip

Release Date: 2/2/2020

Implementation Date: 2/28/2020

<i>Product</i>	<i>QNumber</i>	<i>QNumber Description</i>	<i>Part Number</i>
KW2 CFLNM1.T	Q65112A1566	KW2 CFLNM1.TG-7P5QF-EBVF46FCBB46-	KW2 CFLNM1.TG-7P5QF-EBVF46FCBB46-
KW3 CGLNM1.T	Q65112A1567	KW3 CGLNM1.TG-6QF5R-EBVF46FCBB46	KW3 CGLNM1.TG-6QF5R-EBVF46FCBB46
KW4 CHLNM1.T	Q65112A1568	KW4 CHLNM1.TG-5R7RF-EBVF46FCBB46-	KW4 CHLNM1.TG-5R7RF-EBVF46FCBB46-